

ABSTRACT

A semiconductor bear chip having a bump subjected to high temperatures is pressed, from the upper side, onto a wiring board including a wiring pattern, a thermosetting resin film 5 covering an electrode area on the wiring pattern and having insulating particles dispersed and included and a thermoplastic resin film covering the thermosetting resin film, while applying a ultrasonic wave, thereby inserting the bumps of the semiconductor bear chip through the thermoplastic resin film 10 and the thermosetting resin film to bond the top end portion of the bump with the electrode area.